

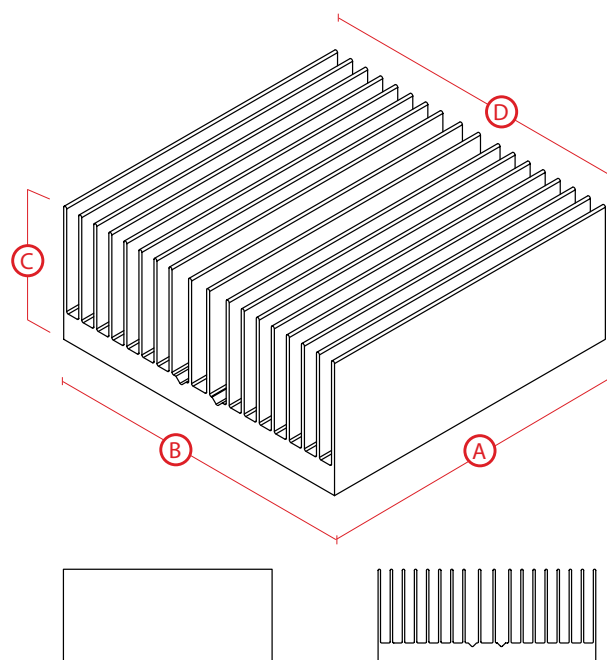


High Performance BGA Cooling Solutions w/ Thermal Tape Attachment

ATS PART # ATS-54400R-C2-R0

Features & Benefits

- » High aspect ratio, straight fin heat sinks that are ideal for compact PCB environments
- » Designed specifically for BGAs and other surface mount packages
- » Comes preassembled with high performance thermal interface material



**Image above is for illustration purposes only.*

Thermal Performance

| AIR VELOCITY | | THERMAL RESISTANCE | |
|--------------|-----|----------------------|--------------------|
| FT/MIN | M/S | °C/W (UNDUCTED FLOW) | °C/W (DUCTED FLOW) |
| 200 | 1.0 | 3.2 | 1.7 |
| 300 | 1.5 | 2.3 | |
| 400 | 2.0 | 1.9 | |
| 500 | 2.5 | 1.7 | |
| 600 | 3.0 | 1.6 | |
| 700 | 3.5 | 1.5 | |
| 800 | 4.0 | 1.4 | |

Product Details

| DIMENSION A | DIMENSION B | DIMENSION C | DIMENSION D | INTERFACE MATERIAL | FINISH |
|-------------|-------------|-------------|-------------|--------------------|----------------|
| 40 mm | 40 mm | 19.5 mm | 40 mm | SAINT-GOBAIN C675 | BLACK-ANODIZED |

NOTES:

- 1) Dimension C = heat sink height from bottom of the base to the top of the fin field.
- 2) Thermal performance data are provided for reference only. Actual performance may vary by application.
- 3) ATS reserves the right to update or change its products without notice to improve the design or performance.
- 4) Contact ATS to learn about custom options available.



For more information, to find a distributor or to place an order, visit www.qats.com or call: 781.769.2800 (North America); +31 (0) 3569 84715 (Europe).